



## High Precision Semi Automatic BGA Rework Station with 5200W Power for Motherboard Repair and Reballing

Our Product Introduction

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### Basic Information

- Place of Origin: CHINA
- Brand Name: WISDOMSHOW
- Certification: CE, ISO, FDA
- Model Number: WDS620
- Minimum Order Quantity: 1

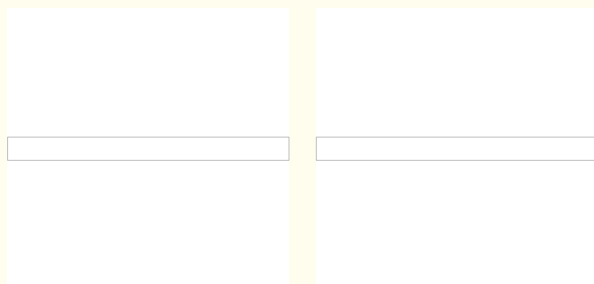


### Product Specification

- Max Mounting Load: 150g
- Type: Semi Automatic
- Mounting Accuracy:  $\pm 0.01\text{mm}$
- Weight: 12kg
- Weight Of Machine: 60KG
- Chip Size: Min 1\*1mm
- Apply Chip Size: 0.8\*0.8~120\*120mm
- Maximum Mounting Load: 150G
- Applicable Pcb Thickness: 0.5-5mm
- The Power Supply: 5300W
- Bga Chip Size: Max120\*120mm Min 0.8\*0.8mm
- Application: BGA (Ball Grid Array) Rework
- Pcb Size: Max. 470x380mm
- Core Components: PLC
- Voltage: 220V



### More Images



## Product Description

### Hot Air Infrared Combo BGA Rework Station WDS620

**High Precision BGA Reballing Machine** - WDS 620 BGA Reballing Machine, AC 220V BGA Soldering Machine

### Technical Specifications

Power Supply	AC 220V $\pm$ 10% 50/60Hz
Total Power	5200W
Upper Heater Power	Max 1200W
Lower Heater Power	Max 1200W
IR Heater Power	Max 2700W

### Detailed Parameter Specification

Power Supply	AC 110V/220V $\pm$ 10% 50/60Hz
Total Power	Max 5300W
Heater Power Distribution	Upper zone: 1200W, Second zone: 1200W, IR zone: 2700W
Electrical Components	Driving motor + PLC smart temperature controller + color touch screen
Temperature Control	High precision K-sensor (Closed Loop), independent temperature controller, precision $\pm$ 1
Positioning System	V-shape slot, adjustable PCB support jigs, laser light for fast centering and positioning
PCB Size Range	Max 500*380mm, Min 10*10mm
Applicable Chip Sizes	Max 80*80mm, Min 1*1mm
Overall Dimensions	650*630*850mm (L*W*H)
Temperature Interface	1 unit
Machine Weight	60KG
Color	White & Blue

### Advanced Operating Modes

The WDS-620 features 5 operational modes: Remove, Mount, Weld, Manual, and Semi-auto. Operators can freely switch between automatic, semi-automatic, and manual operation modes.

### Independent 3-Zone Temperature Control System

- Upper and lower hot air heating simultaneously targets components and PCB
- Bottom IR heating with temperature precision control within  $\pm$ 1
- 8-segment independent temperature control system
- Hot air district heating for BGA and PCB simultaneously
- Large area IR heater preheating prevents PCB deformation during rework
- Upper and lower temperature zones can operate independently or combined
- High precision K-type thermocouple closed-loop control with PID parameter self-setting
- 4 temperature curves display with instant analysis function
- Multiple user data profiles can be saved
- External measurement interface for precise temperature testing

### Precision Optical Alignment System

High-definition adjustable CCD color optical alignment system with beam split, amplification, reduction, and auto-focus capabilities. Features automatic color aberration resolution, brightness adjustment, and adjustable image contrast. Equipped with 15" high-definition LCD monitor.

## Multi-Functional Operation System

High-definition touch human-machine interface

Upper heating head and mounting head designed as 2-in-1 unit

Multiple titanium alloy BGA nozzles with 360-degree rotation

X, Y, and R angle micrometer fine-tuning with  $\pm 0.01$  mm precision

## Safety Protection Features

Automatic alarm function after BGA welding completion

Automatic circuit power-off during temperature abuse conditions

Dual over-temperature protection system

Temperature parameter password protection to prevent unauthorized modifications



**Shenzhen Wisdomshow Technology Co.,Ltd**



+86 18926538696



elysia.li@wdsbga.cn



bgaxraymachine.com

No.6,Haosi Western Industry,Shangjing Town,Bao'an District,Shenzhen,China